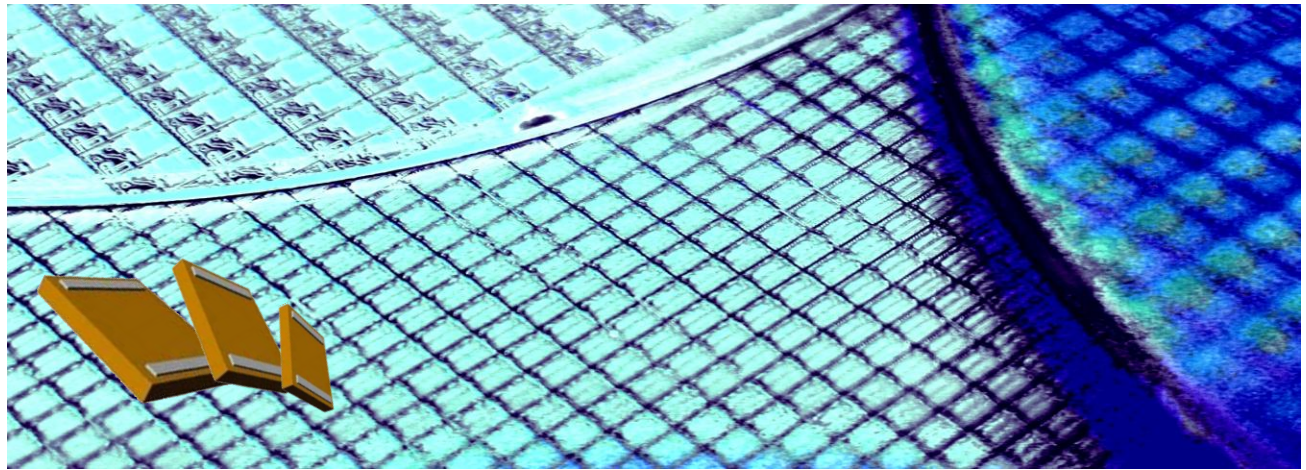


Manual Handling recommendation



These capacitors are designed to be mounted with a standard pick and place machine, with reflow.

In case of manual handling, please follow below recommendations:

- Minimize mechanical pressure on the capacitors (use of a vacuum nozzle is recommended).
- Minimize temperature shocks (pre-heat the substrate).
- No wirebonding on 0402 47nF, 0402 100nF, 1206 1 μ F, 1812 3,3 μ F

Process steps:

- On substrate, form the solder meniscus on each land pattern targeting 100 meniscus height after reflow (screen printing, dispensing solder paste or by wire soldering).
- Pick the capacitor from the tape & reel or the Gel Pack keeping backside visible using a vacuum nozzle.
- Temporary place the capacitor on land pattern assuming remaining flux will stick the capacitor.
- Reflow the assembly with a dedicated profile (see reflow recommendation profile)
- After soldering, no solder paste should touch the side of the capacitor dies.

If you have any questions prior to mounting the capacitors, please contact IPDiA (contact details below) and ask for our assembly specialist.

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